

SMT Capabilities:

Stencil size range : 1300*450mm

Min. SMT package : 01005

Component range: Chip(from 01005), SOIC, SOT, SOD, TSOP,MELF, CSP, QFP(low profile), DPAK, flip chip, odd-shape

Component specification: min: 0.4 x 0.2 mm (0.016" x 0.008") (01005) max: 56 x 56 x 2.54 mm (2.20" x 2.20" x0.10") max: component weight: 140 g

Maximum board size : 500 x 580mm

Minimum board size : No Limited

Max. component height: 25mm

Board thickness range : 0.1 - 8.0mm

Board edge clearance top and bottom:3.2 mm

Chip Accuracy :75um, 26°

Min. IC pitch : 0.3mm

Max. BGA Size :73*73mm

BGA ball pitch BGA :1.00 to 3.00mm

BGA ball diameter BGA: 0.4 to 1.0mm

QFP lead pitch QFP :0.38 to 2.54mm